

Electronic Acknowledgement Receipt

EFS ID:	1038415
Application Number:	10814482
Confirmation Number:	6082
Title of Invention:	Method for fabricating strained silicon-on-insulator structures and strained silicon-on insulator structures formed thereby
First Named Inventor:	Toshiharu Furukawa
Customer Number:	30206
Filer:	William R. Allen/Susan Daczko
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		IBM-293_Response_Restriction.pdf	217632	yes	5

	Multipart Description		
	Doc Desc	Start	End
	Response to Election / Restriction Filed	1	1
	Claims	2	4
	Applicant Arguments/Remarks Made in an Amendment	5	5
Warnings:			
Information:			
Total Files Size (in bytes):		217632	
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